



# The IIHE Contribution to the CMS Silicon Strip Tracker Upgrade

IIHE Annual Meeting 2025

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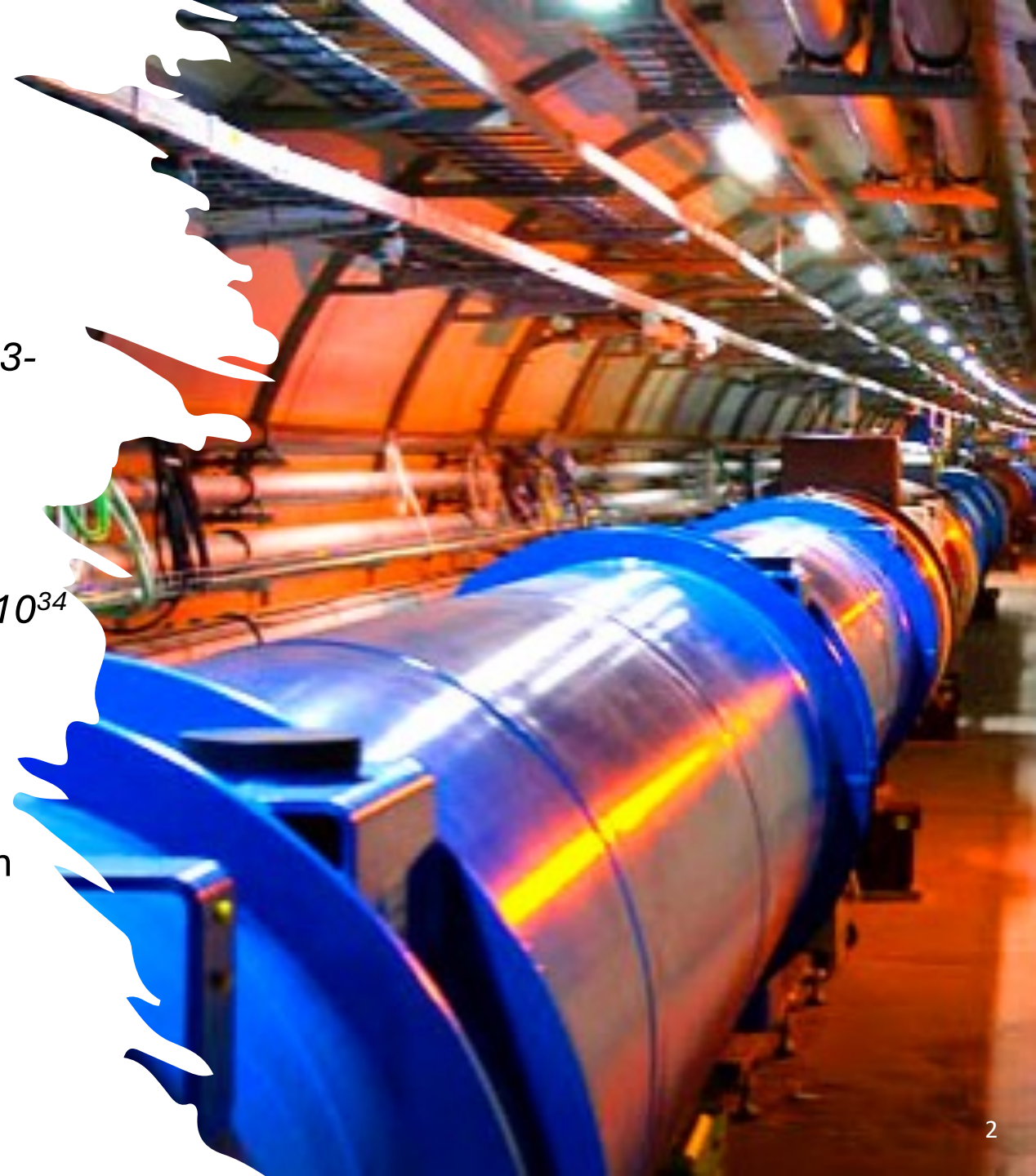


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# The HL-LHC :

- The LHC is getting upgraded

- Increase in **Integrated luminosity** from  $450fb^{-1}$  to 3- $4000fb^{-1}$ 
  - High **radiation damage** to the detector
- Increase in Instantaneous luminosity from  $2.2 \times 10^{34} cm^{-2} S^{-1}$  to  $5-7.5 \times 10^{34} cm^{-2} S^{-1}$ 
  - Average **pile-up** increases from 65 to  $\sim 200$ .
- To cope with this **high pile-up** and **radiation** condition  
**we need better detector**



# CMS Upgrade:

## New Tracker

- Tracks in hardware trigger (L1) up to  $\eta \sim 2.5$
- Coverage closer to the beam (up to  $\eta \sim 4$ )
- More precise momentum and impact parameter
- Radiation tolerant - high granularity - less material

## New Endcap Calorimeters

- Radiation tolerant
- High granularity

## Muons

- Complete resistive plate chambers coverage in forward region
- Extend coverage up to  $\eta \sim 2.8$
- Replace electronics

CMS  
extensive upgrade for  
precision H boson  
physics  
extended acceptance  
for beyond-standard  
model physics

## Barrel ECAL

- Replace electronics
- Cool crystals/photodetectors

## Barrel HCAL

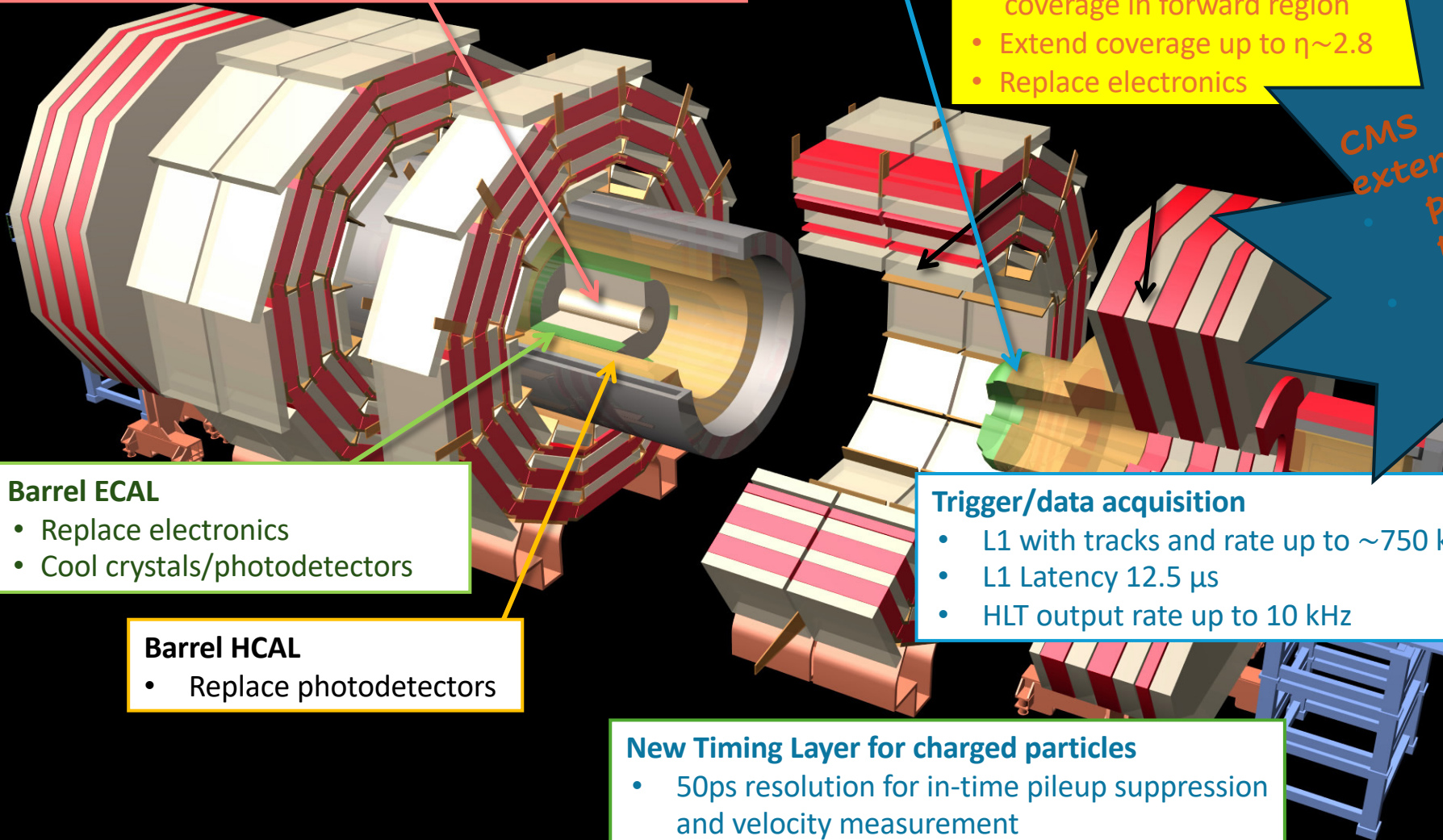
- Replace photodetectors

## Trigger/data acquisition

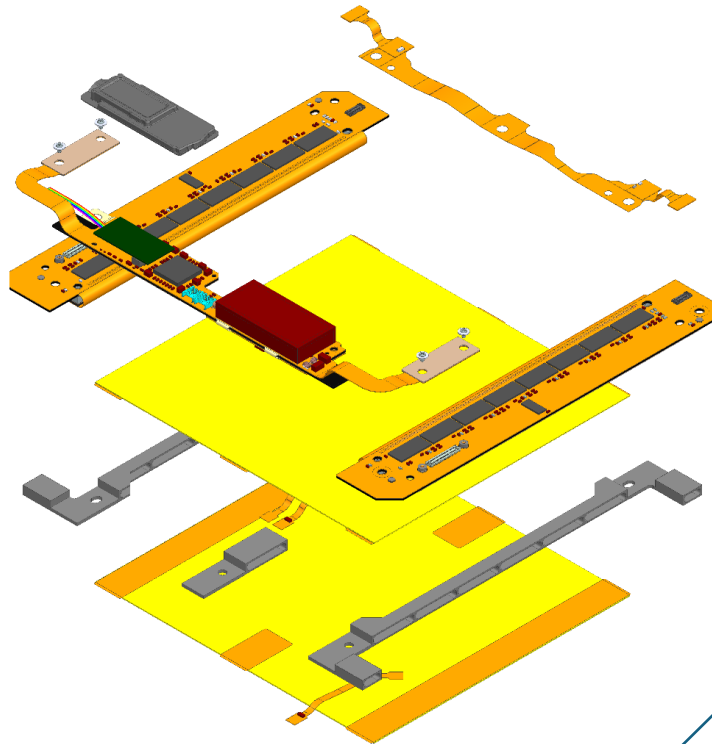
- L1 with tracks and rate up to  $\sim 750$  kHz
- L1 Latency  $12.5 \mu\text{s}$
- HLT output rate up to 10 kHz

## New Timing Layer for charged particles

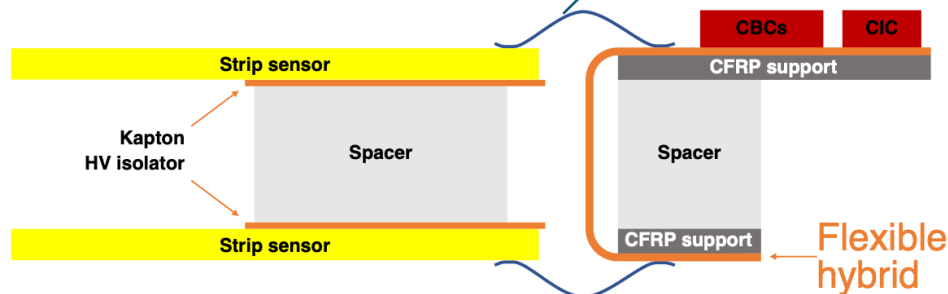
- 50ps resolution for in-time pileup suppression and velocity measurement



# Focus on Phase 2 Upgrade of CMS Outer Tracker

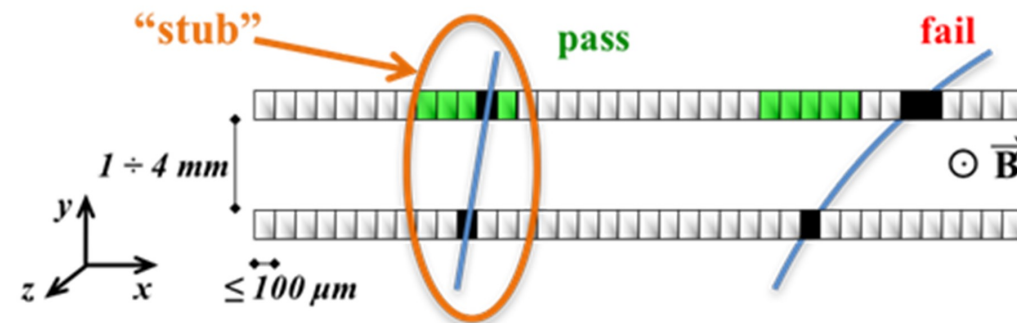


Wire  
bonds



- Tracking triggering at Level1

- Correlated hits on two closely placed silicon sensors
- Predefined window on the second sensor discards low transverse momentum particles
- This concept is called “track stub”





# Outer tracker modules for Phase 2

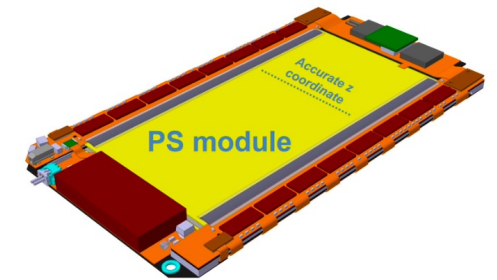
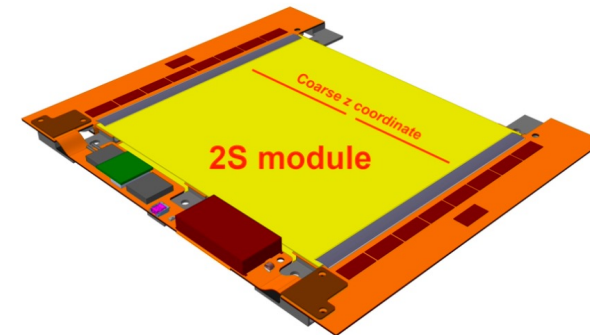
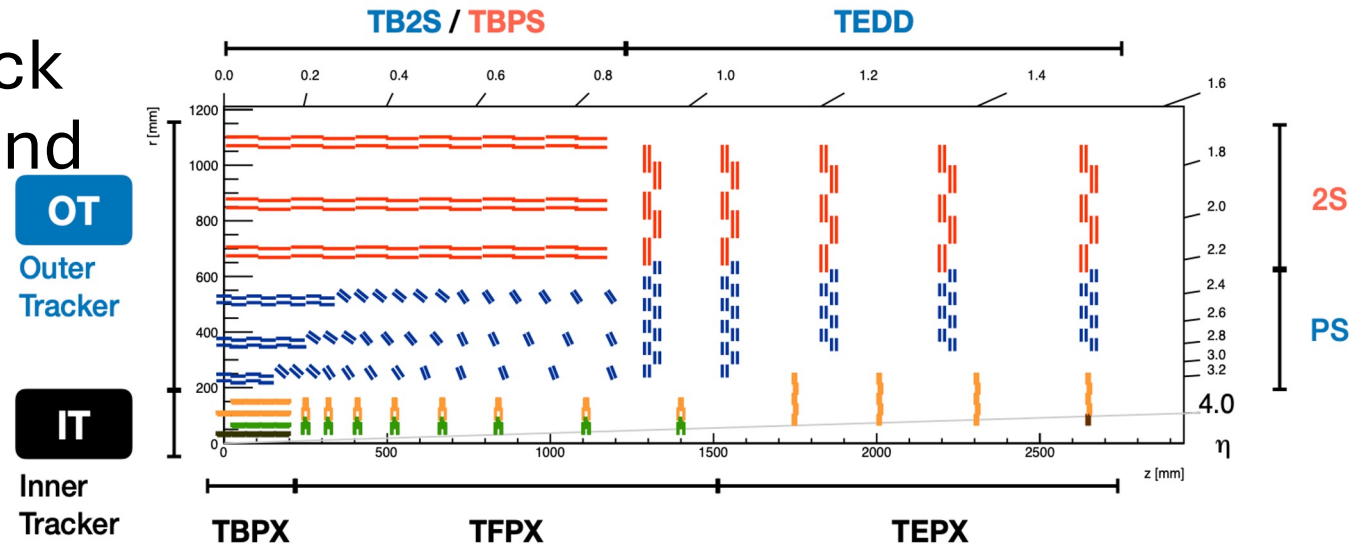
- There are two different types of track stub modules organized in barrel and endcaps

- Strip-Strip(2S) module**

- ~90cm<sup>2</sup> area per sensor
- 2x1016 strips: 5cm x 90μm per sensor
- Forming the outer layers/rings

- Pixel-Strip(PS) module**

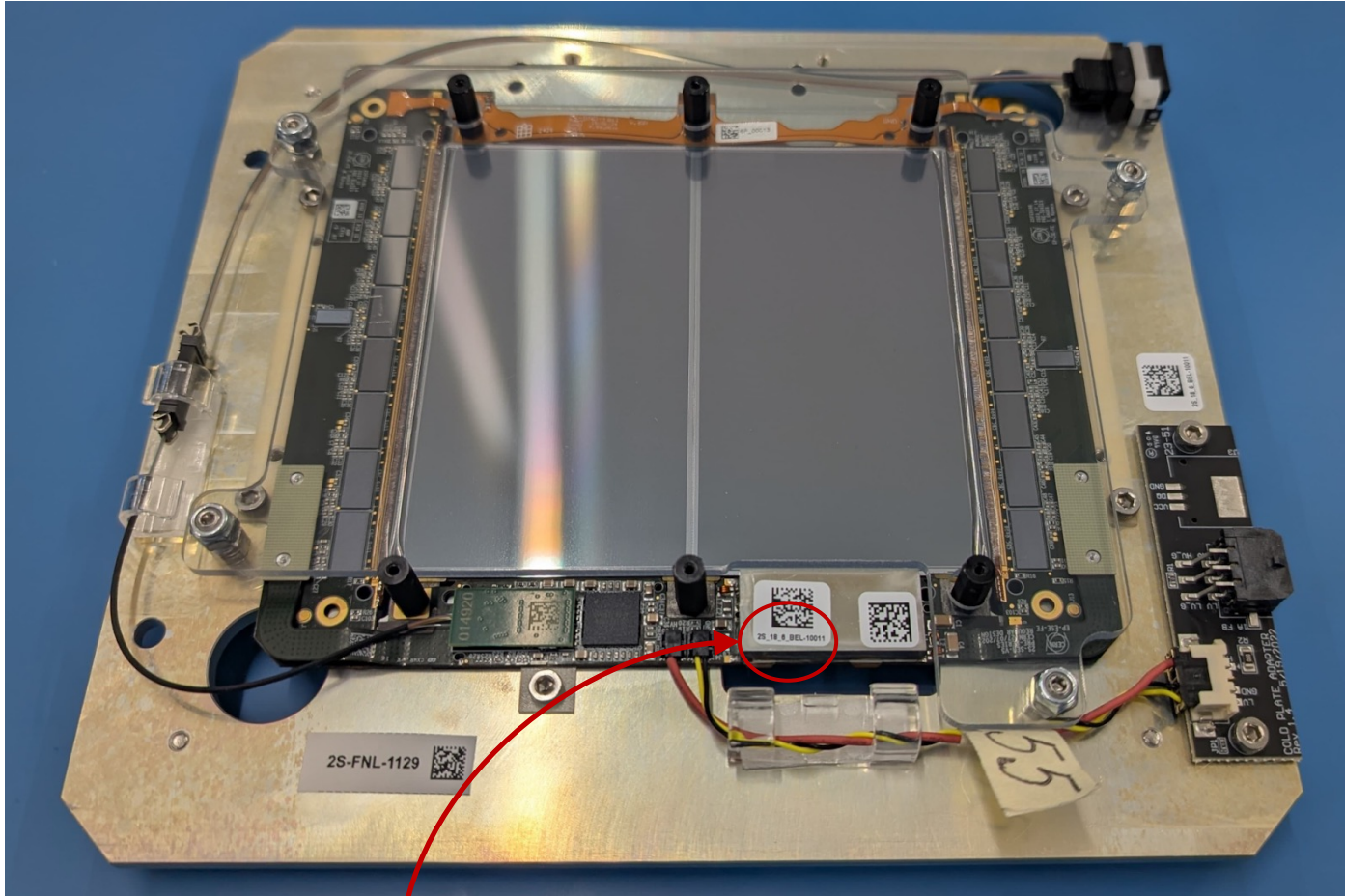
- ~2 x45 cm<sup>2</sup> active area
- 2 x960 strips: ~2.4 cm x 100 μm
- 32 x960 macro-pixels: ~1.5 mm x 100 μm
- Forming the inner layer/rings



**Total 13200 modules: 2S(7608), PS(5592)**

**- Being assembled in multiple centers across world**

# How a 2S module looks after the assembly at IIHE



18 : 1.8mm sensor spacing  
6 cooling points  
BEL assembly site  
production label 10011

2S\_18\_6\_BEL\_100011

# Belgian contribution to the CMS phase-2 tracker upgrade

- ✓ Team of >35 people from Universiteit Antwerpen, Universiteit Gent, Université Libre de Bruxelles, Vrije Universiteit Brussel collaborated at IIHE to:
  - ✓ Deploy 1 out of the 7 module production sites
  - ✓ **Build 1523 2S modules** + spares and test them fully
- ✓ Setting up and building facilities started 2016
- ✓ **Built more than 150 modules** already as of October 2025.
- ✓ In September we reached our **nominal throughput of 24 modules per week.**
- ✓ Integration and test of Dees and double disks (DD): in UCLouvain



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UCLouvain



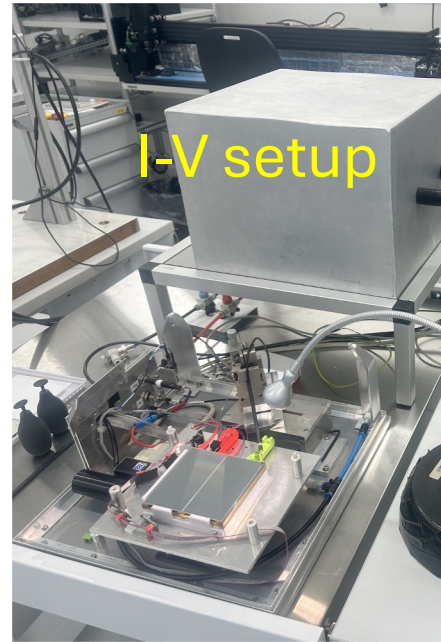
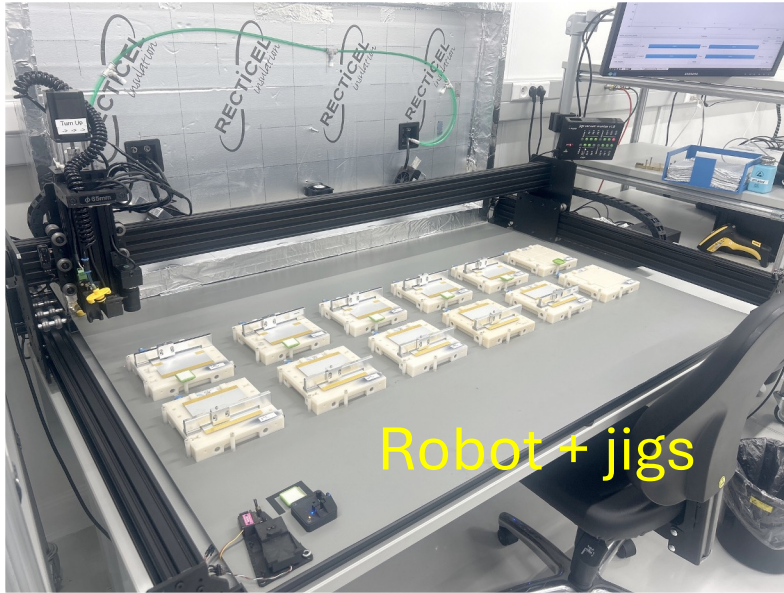
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# 2S module production site at IIHE



- **Local developments started in 2017**
  - clean room, glue doser, gluing robots, Si I-V setup, metrology, one type of jig (also for other 2S sites)
  - local database, production planner, GUI's
- Other jigs, setups for functional tests (KIT design), thermal cycling setup (Fermilab design)
- Industrial wire bonding equipment; high-end digital microscopes; dry storage,...
- Capacity of 6 modules per day

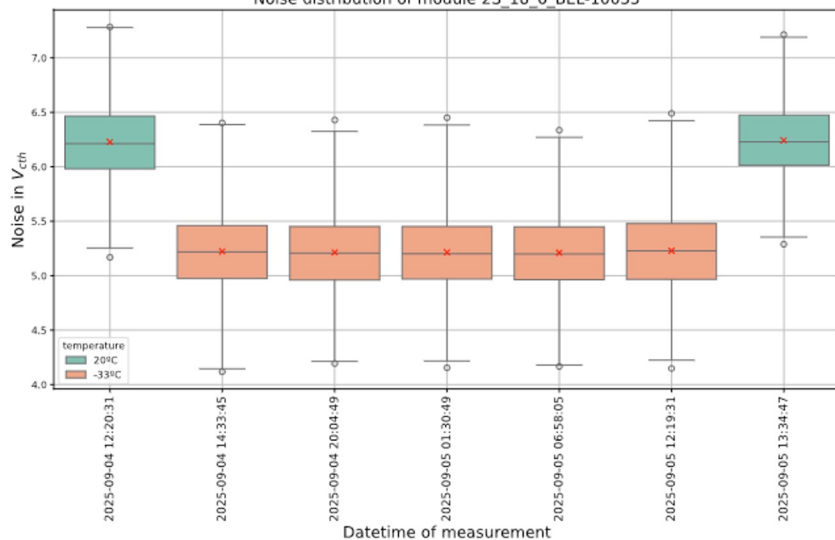


# We make fine modules...

Two thermal cycling setups in Belgium  
at IIHE



Noise distribution of module 2S\_18\_6\_BEL-10033



at UCLouvain



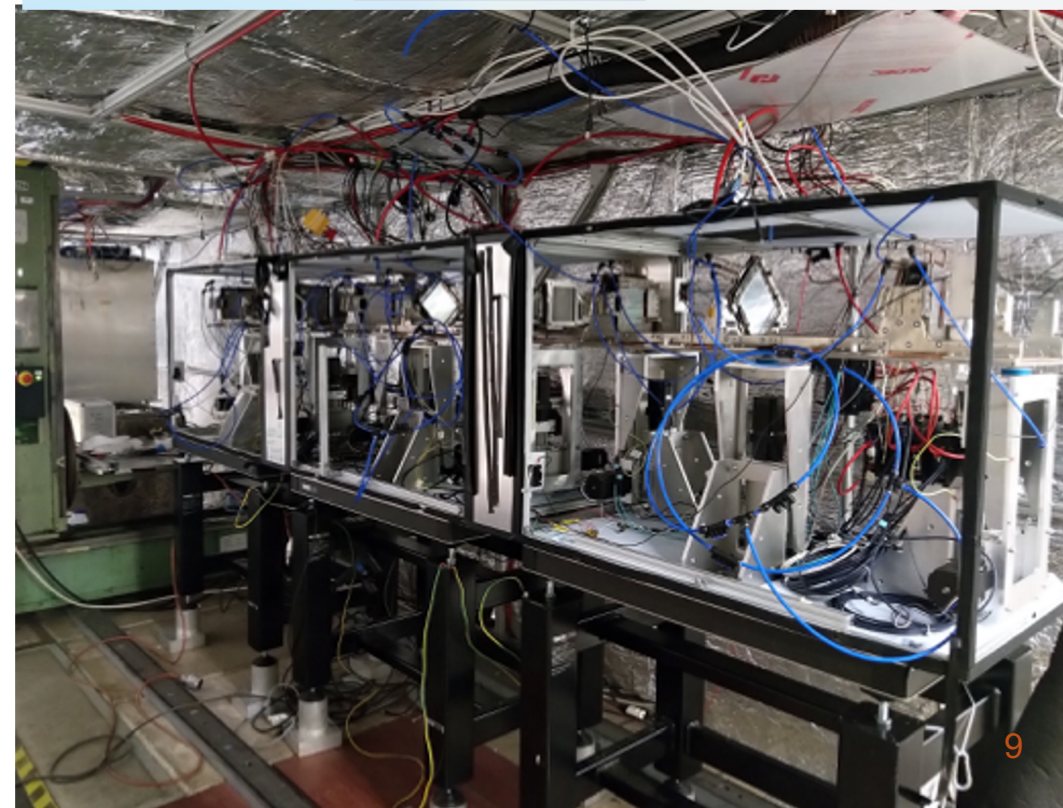
Noise of a module  
at 20°C and -33°C  
during 5 thermal  
cycles

MUonE 2025 test run

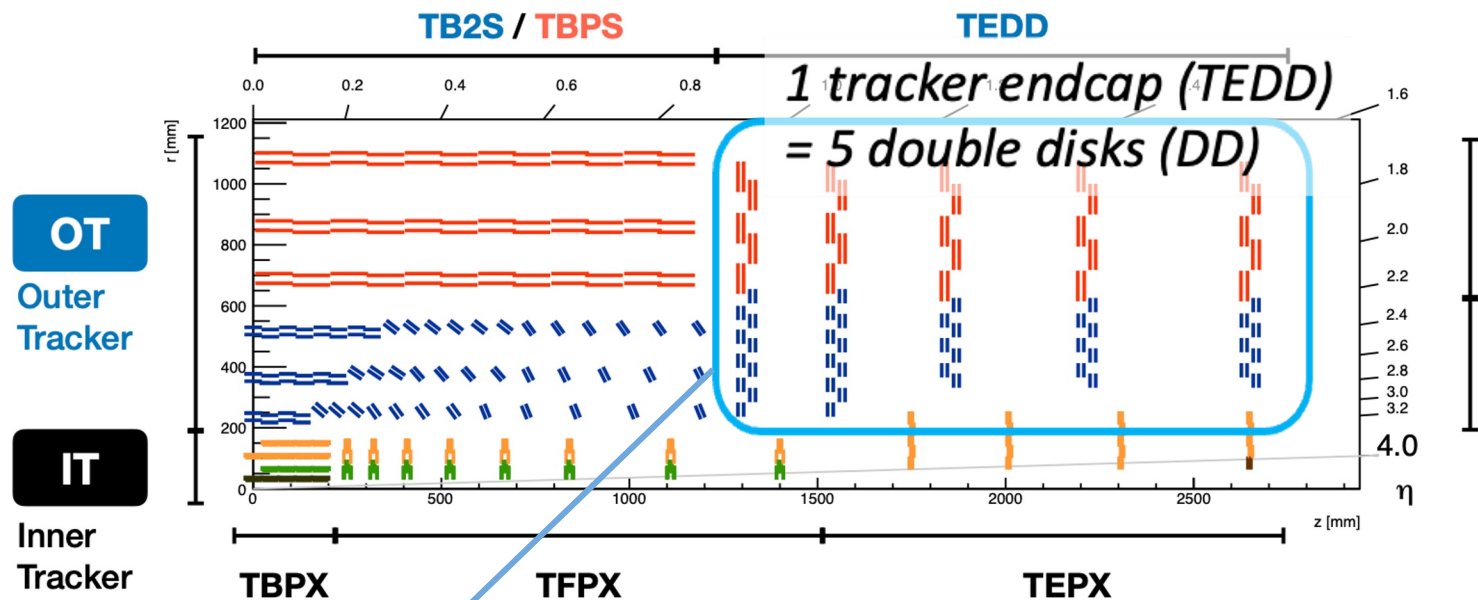
7(→6) production modules out of 18

STATION 1		STATION 2		STATION 3	
X0	2S_18_6_KIT-01002	X0	2S_18_6_BEL-10004	X0	2S_18_6_KIT-10005
Y0	2S_18_6_BEL-01002	Y0	2S_18_6_BEL-10005	Y0	2S_18_6_KIT-10001
U	2S_18_5_BRN-01001	U	2S_18_6_BEL-10002	U	2S_18_6_KIT-10002
V	2S_18_6_BRN-10001	V	2S_18_6_BEL-10003	V	2S_18_6_KIT-10006
X1	2S_18_6_KIT-10004	X1	2S_18_6_BEL-10009	X1	2S_18_6_KIT-10003
Y1	2S_18_5_KIT-10001	Y1	2S_18_6_BEL-10010	Y1	2S_18_6_BEL-10001

2S\_18\_5\_NIS-10001

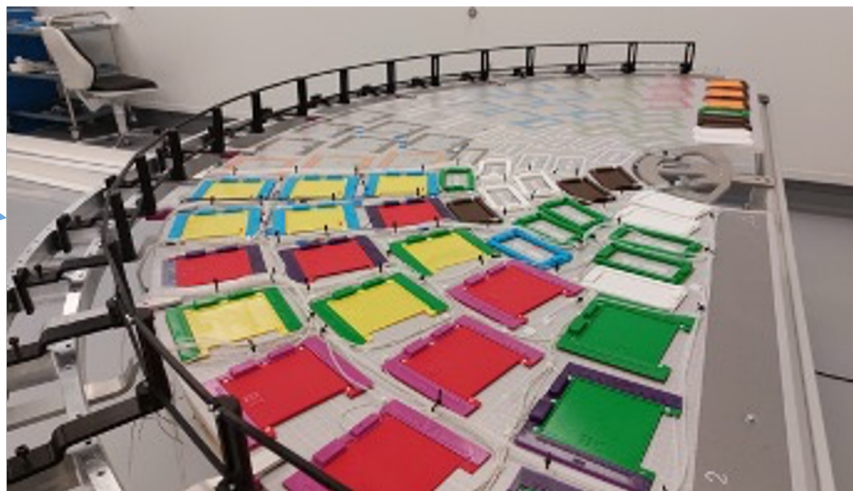
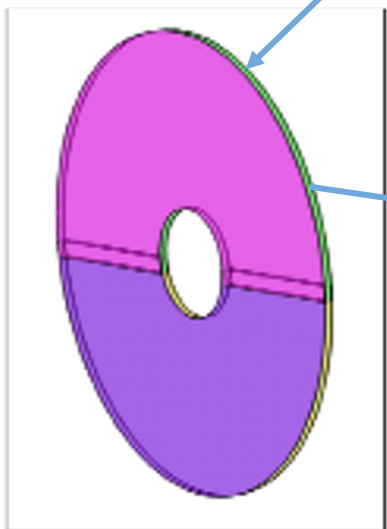


# Dees and Double-Disks



1 DD = 4 Dees

1 Dee = 170 modules

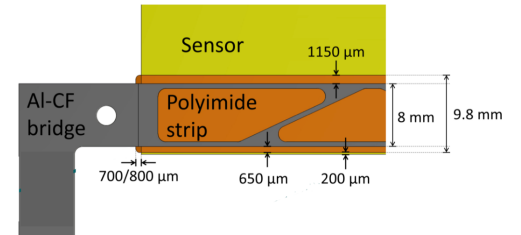


## In UCLouvain:

- Design TEDD services
- Design Dee integration process and deploy 1 Dee integration facility
- Integrate 12 Dees
- Deploy 1 of the 2 DD integration facilities
- Integrate 5 DD
- Services design was validated with mockups
- First Dee integration test done in April together with DESY and Lyon teams
- Dee test box is functional
- DD assembly was exercised successfully

# Current Challenges and Issues:

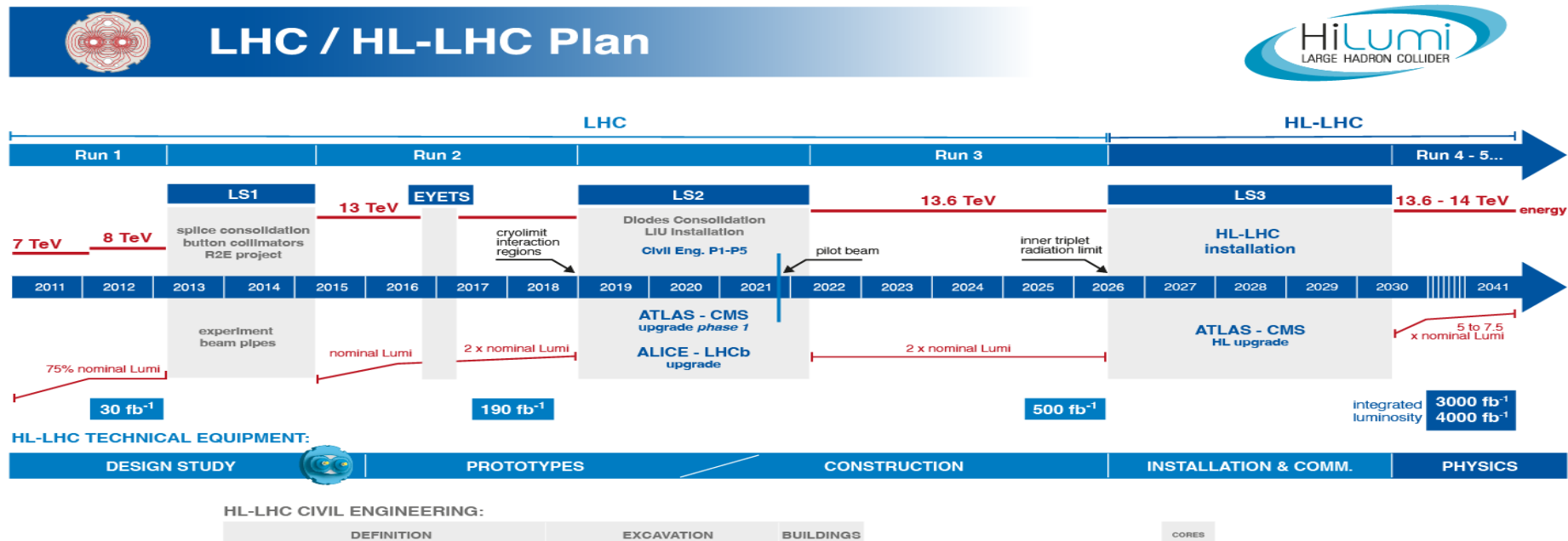
- **Back End Power On Logic (BPOL12V) failure:**
  - Local 12V DC-DC voltage converter in modules seems to fail/misbehave after irradiation and multiple power cycles
  - Chip that is used in all HL-LHC experiments and in most parts of each experiments
- **Ground pin contact issue in Font End Hybrid(FEH):**
  - Seems to be loosing contact with CF structure.
  - Additional soldering solves the issue.
- **Sparking between Service End Hybrid(SEH) and the sensor:**
  - Observed in High Voltage when SEH is too close to sensors
  - Solved with additional Kapton strip Isolator attached at the edge of SEH
- **Kapton isolator flim positioning accuracy:**
  - Inaccurary may lead sparking between sensor and Al-CF spacors.
  - Very crucial specially with high througput
  - Image proccessing system being developed to monitor and ensure accuracy





# Summary:

- With HL-LHC, CMS Outer tracker is getting huge upgrade
- Financially and person power-wise, the largest Belgian contribution to a HEP project so far
- Our modules are performing well in MUonE test beam and in integration tests
- Learnt lessons from non-compliant modules and improvement being implemented
- Despite local and central challenges, we are determined to keep running our schedule





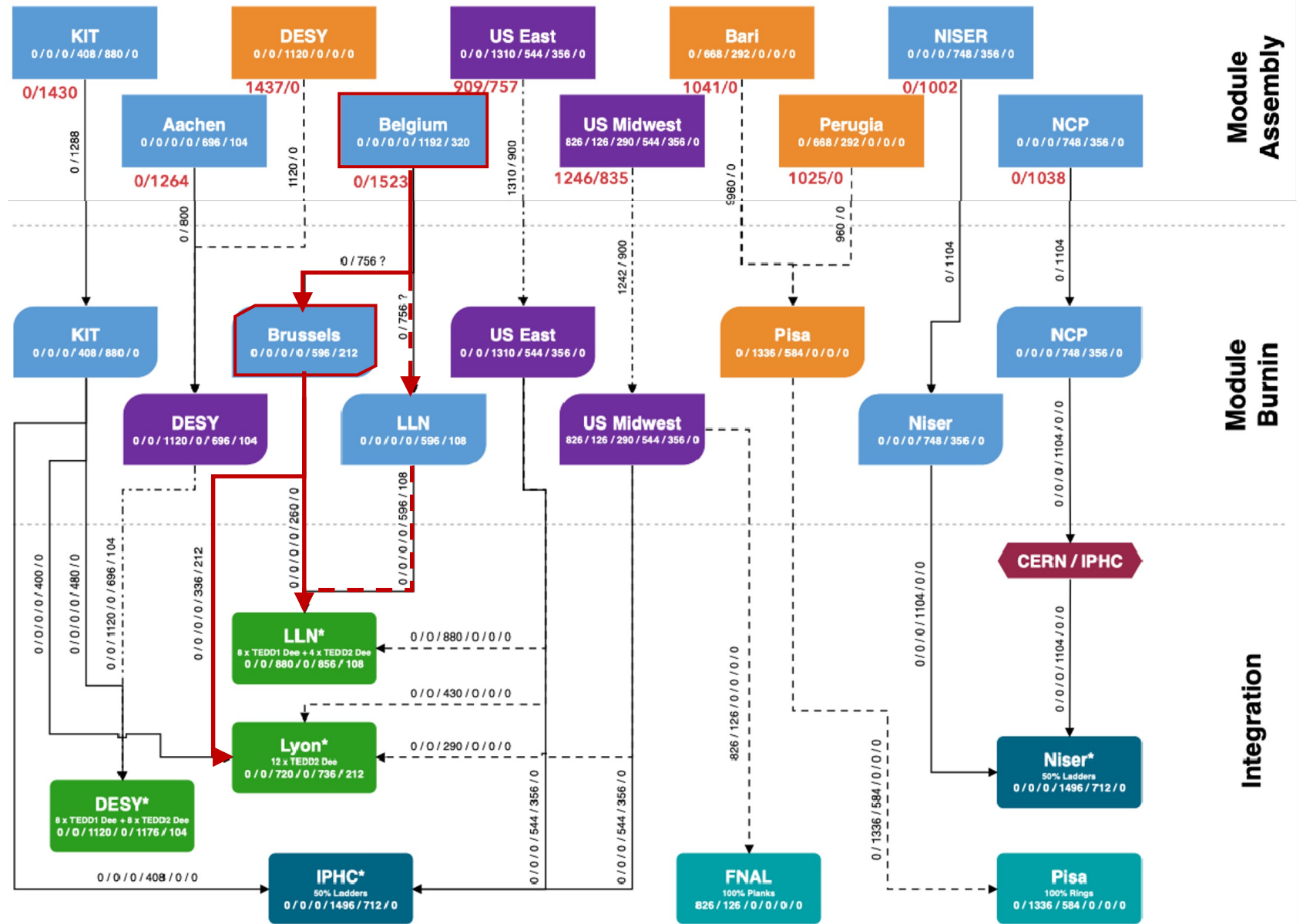
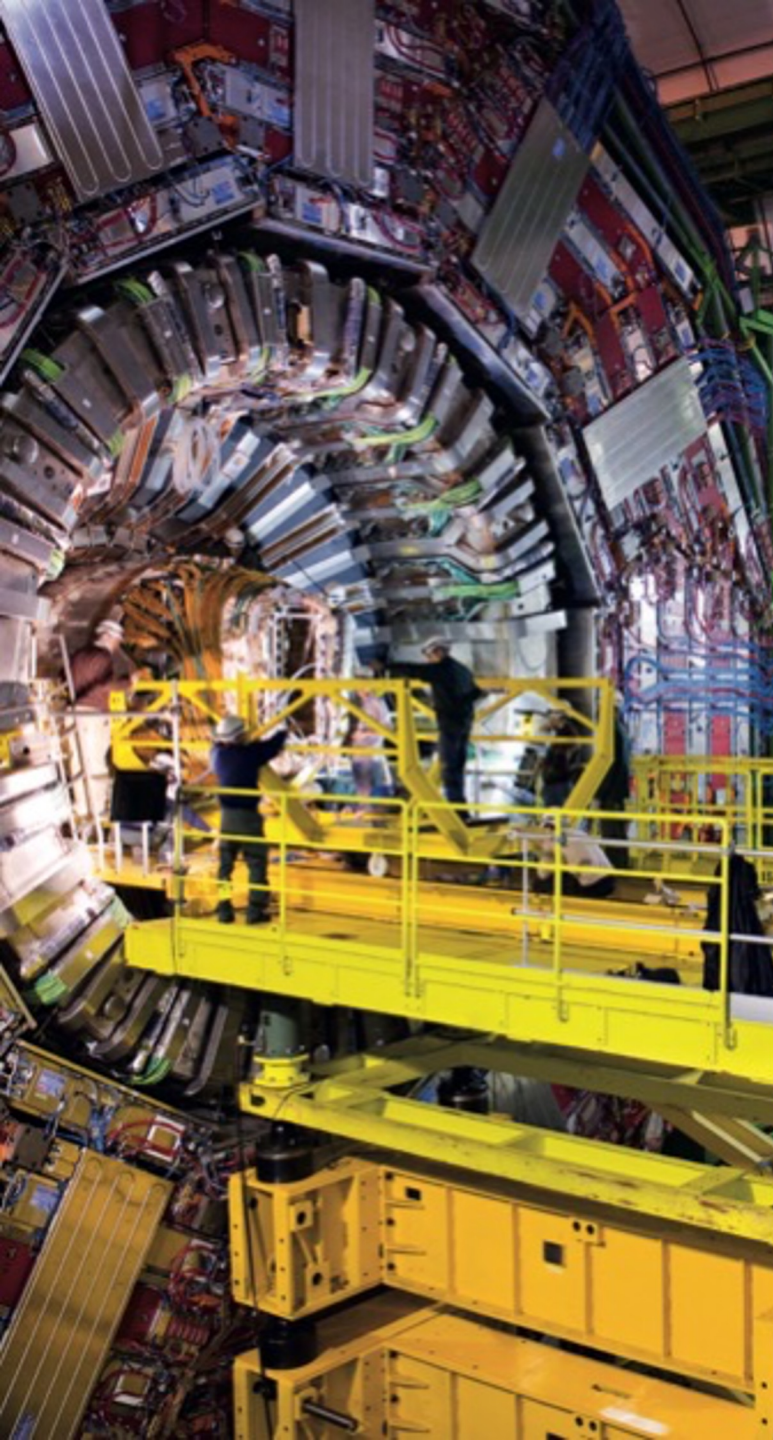
Thank you for your attention



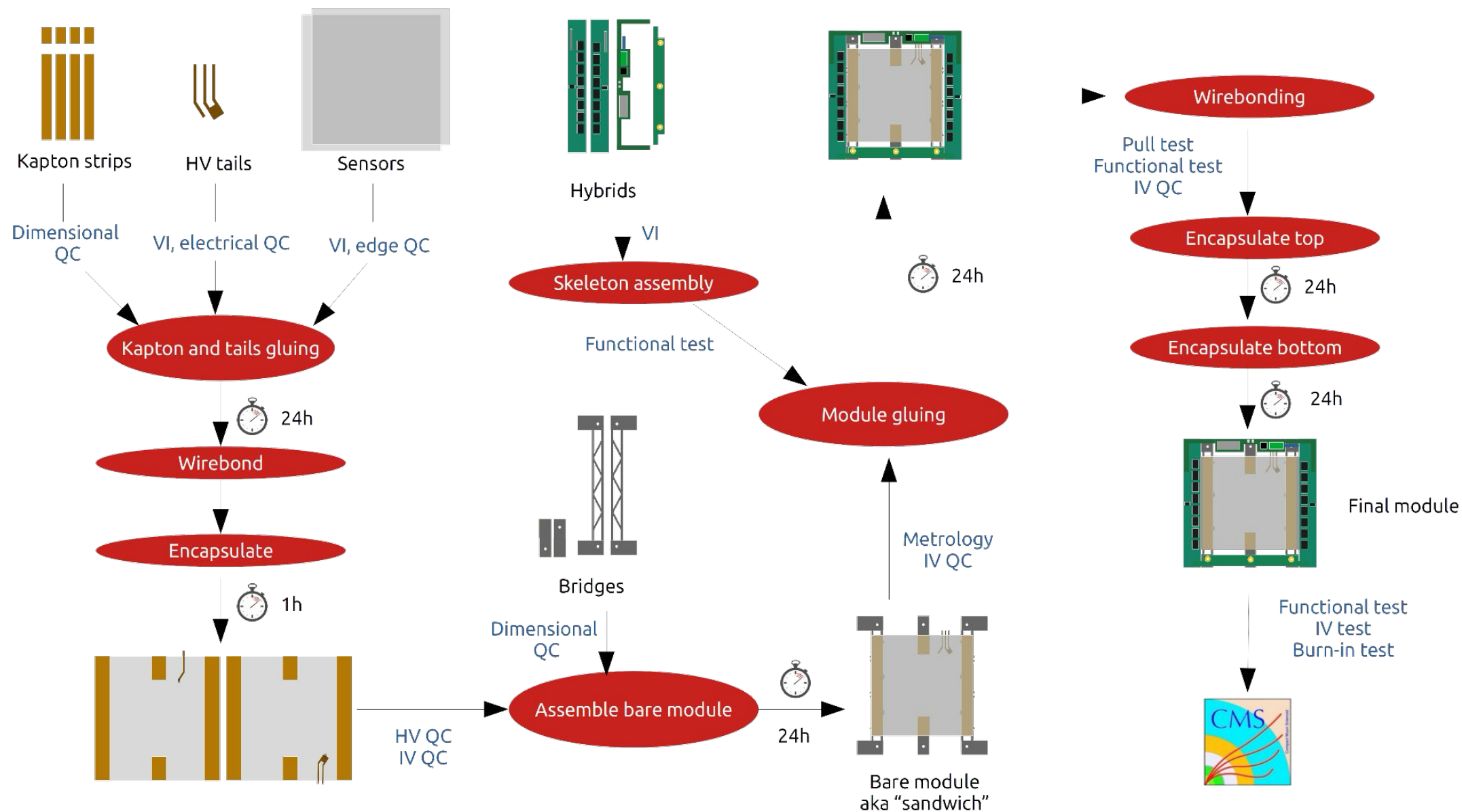
CMS Spoke person visit to our cleanroom

# Back Up





# 2S module assembly procedure

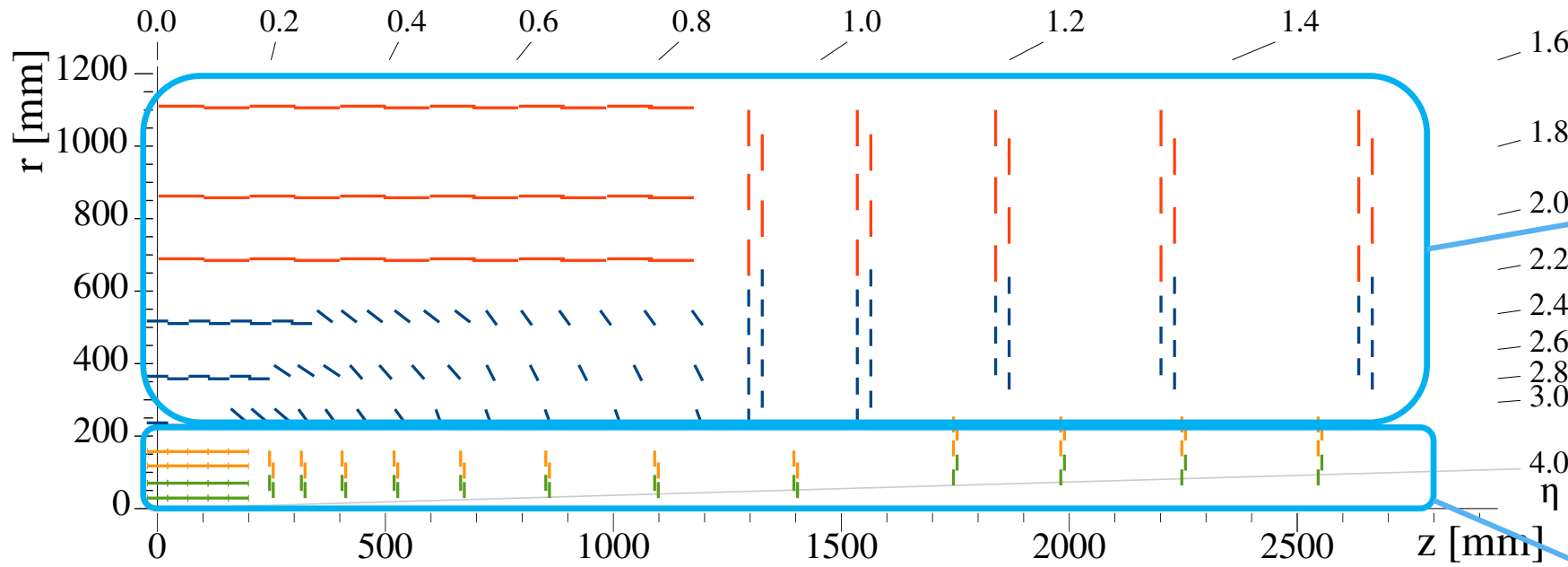




# Our center specific development to ease the assembly process

- Production planner and Local database
  - Eases the task planning, book keeping of every parts and incidents
- Glue dosing system, Centrifugule to remove glue bubble
  - Eases the process of glue preparing and updating log in database
- Two self made gluing robot
  - one for kapton isolator gluing and other one for encapsulation of wire bonds, Kapton isolator gluing jig
- Glue curing system
  - To make sure the glue is cured in time
- Microscope on rails to monitor the sandwich gluing and hybrid gluing
- Metrolgy to test mechanical precision of the module
  - Autofocusing and Pattern Recognition and flexibility to easily switch between different category of 2S modules (4mm and 1.8 mm)

# Tracker

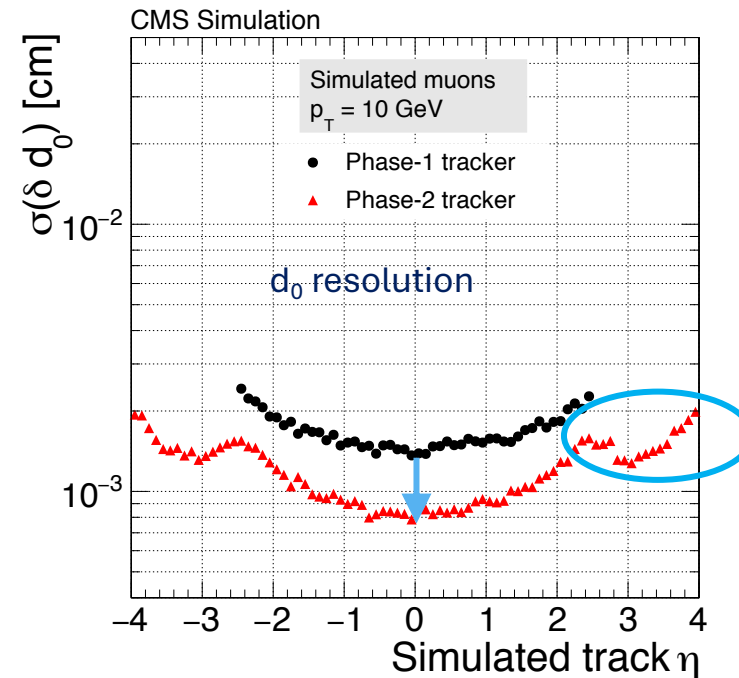
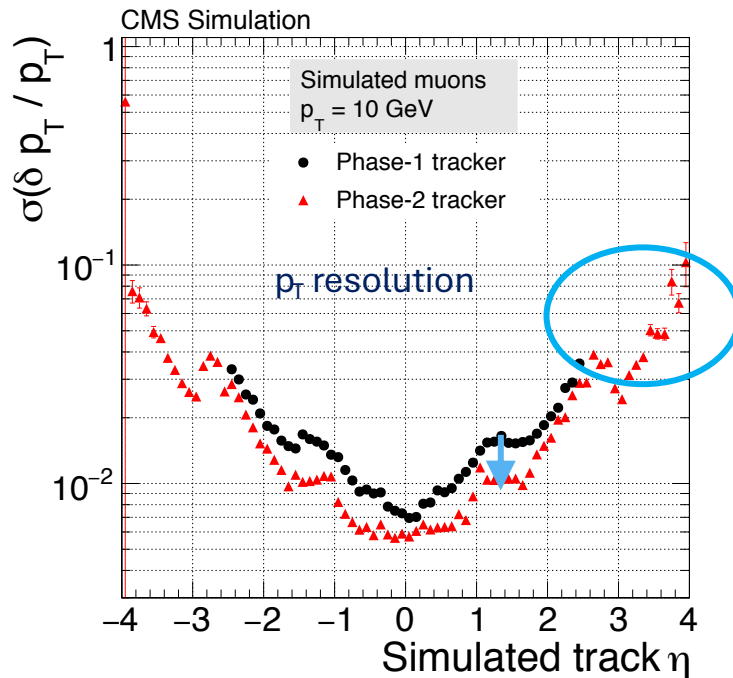


## Outer tracker

- “ **$p_T$  modules**” with 2 sensors read out together
- **Tracking at 1<sup>st</sup> trigger level** down to  $p_T \sim 2 \text{ GeV}$ ,  $|\eta| \sim 2.5$

## Inner tracker

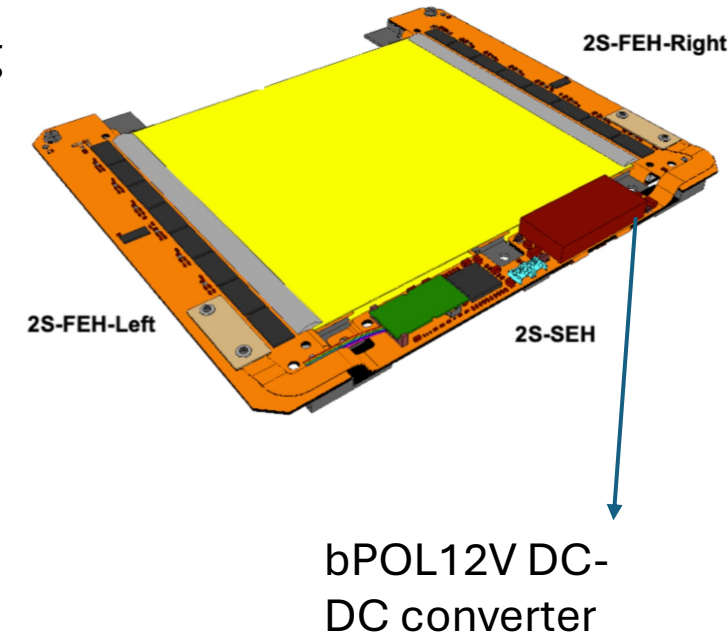
- **6x smaller pixels than Phase-1 pixel detector**
- **coverage up to  $|\eta|=4$**



- More precise track parameters compared to Phase-1 tracker
- Extended coverage, allowing e.g. better forward jet reconstruction

# Back End Power On Logic (BPOL12V) Radiation-Induced Failures:

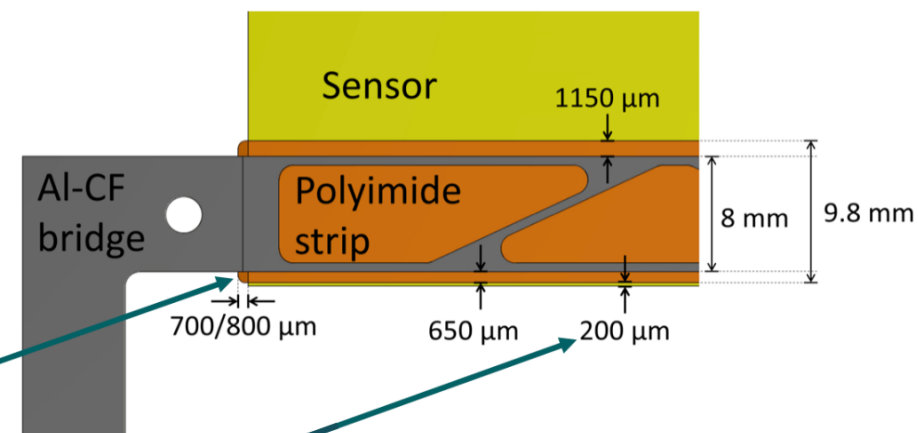
- **Function:**
  - Converts 12 V bus to 2.5 V for OT/IT modules.
  - Feeds second-stage buck converter (bPOL2V5) → supplies final ASIC voltages.
- **Issue**
  - Failures observed after Co-60 irradiation (35–70 MRad) during thermal cycling (ATLAS ITk, Summer 2025).
- **Investigations**
  - Failure traced by ATLAS teams in Freiburg.
  - Reproduced by CERN EP-ESE team using X-ray tests at B14.
  - CMS groups confirmed similar effects in irradiated 2S-SEHs and PS-POHs (protons 2023/24, neutrons 2022).
- **Observed Symptoms**
  - Input voltage spikes at power-on, worsening with thermal/power cycles.
  - Partial shorting between switches, more severe  $< -30\text{ }^{\circ}\text{C}$ .
  - Failures accelerate at cold; annealing at room temperature further degrades devices.
  - Problem understood at chip level and can not be used in the presently foreseen way.
- **Impact**
  - Critical for OT & IT modules operating in high-radiation, sub-zero regions of CMS.
  - Significant delays to be expected for CMS Phase-2 upgrades



# Kapton positioning in the module:

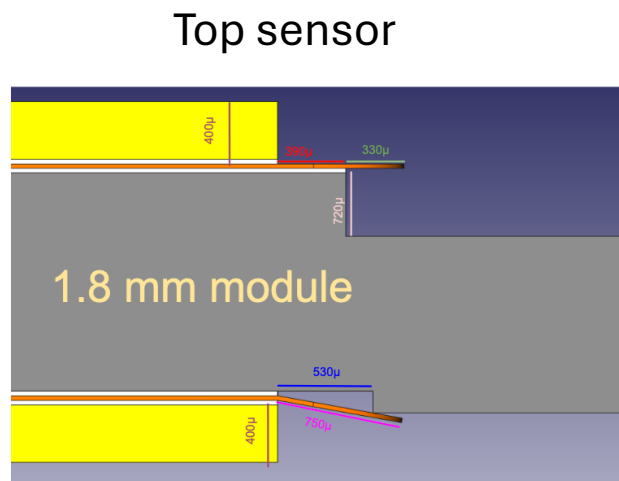
- Kapton strips are thermally conductive but act as electrical isolator between the CF spacer and the sensor backplane as well as sensor edge

Sensor edge to sticking out  
kapton edge  
 $700\mu - 200/+200\mu$

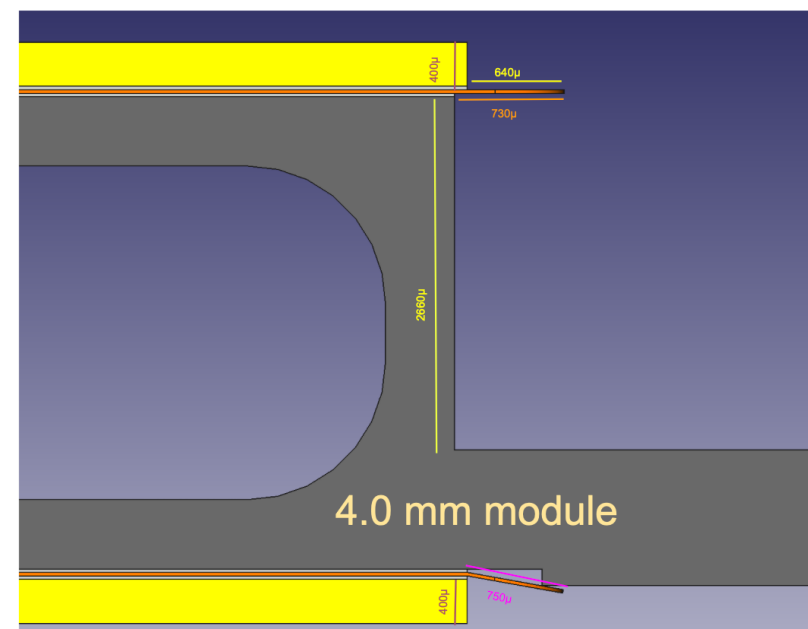


Top sensor

Kapton to sensor edge:  
 $200\mu, -200/+150\mu$



Bottom sensor



Bottom sensor



# Dee and DD integration at UCLouvain

- Services design was validated with mockups
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